



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STOD32WJR	MZN0*UAP5BFA	A	SH1A	2016-04-26
Amount	UoM	Unit type	ST ECOPACK Grade	
2.96	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	260	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC105)	Tin/Silver/Copper (Sn/Ag/Cu)	NAC		

Package Designator	Size	Nbr of instances	Shape	
WAFER	1.64 - 1.74 - 0.3	12	bulk solder	
Comment	Package: CSPS0.4 11-16			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MZN0*UAP5BFA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.348	mg	supplier	die	Silicon (Si)	7440-21-3		1.991	mg	847956	796400
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.019	mg	8092	7600
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.113	mg	48126	45200
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	6388	6000
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	1704	1600
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.033	mg	14055	13200
die (s)				supplier	coating	Polyethylene terephthalate	25038-59-9		0.056	mg	23850	22400
die (s)				supplier	coating	Silica, vitreous	60676-86-0		0.056	mg	23850	22400
die (s)				supplier	coating	Epoxy resin	25068-38-6		0.011	mg	4685	4400
die (s)				supplier	coating	Acrylic polymer	9003-01-4		0.011	mg	4685	4400
die (s)				supplier	coating	Carbon black	1333-86-4		0.003	mg	1278	1200
die (s)				supplier	UBM	Copper (Cu)	7440-50-8		0.017	mg	7240	6800
die (s)				supplier	UBM	Titanium (Ti)	7440-32-6		0.003	mg	1278	1200
die (s)				supplier	UBM	Nickel (Ni)	7440-02-0		0.015	mg	6388	6000
die (s)				supplier	UBM	Vanadium (V)	7440-62-2		0.001	mg	426	400
BUMPS	Solder	0.615	mg	supplier	bump	Tin (Sn)	7440-31-5		0.606	mg	985366	242400
BUMPS				supplier	bump	Silver (Ag)	7440-22-4		0.006	mg	9756	2400
BUMPS				supplier	bump	Copper (Cu)	7440-50-8		0.003	mg	4878	1200